

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A semiconductor manufacturing device comprising:

a processing chamber having an opening, the opening being hermetically sealed by bellows and by a vertically movable pedestal to form an internal space for processing semiconductor wafers;

a holder, disposed within said space, for holding a semiconductor wafer, said holder being formed with a plurality of through-holes extending vertically through a front, wafer-carrying side and an ~~opposing~~ opposite, back side of the holder;

a plurality of lift pins disposed in said processing chamber, with one end of each of said lift pins being anchored to said processing chamber, and ~~[[an]]~~ the opposite end of each of said lift pins being free to ~~move in~~ pass through a corresponding one of said through-holes, said lift pins therein being anchored in such a manner that an imaginary plane formed by the tip faces of their free ends has a planarity of 0.5 mm or less;

a plurality of support pieces retained in said space by said pedestal;

said lift pins and said support pieces being therein arranged, and said bellows and said pedestal being configured, such that maximally lowering said pedestal thrusts said lift pins out of said through-holes along said wafer carrying face.

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Reply to Office action of June 15, 2007

Claims 2-5 (canceled)

Claim 6 (previously presented): The semiconductor manufacturing device of claim 1, wherein said bellows are disposed outside said processing chamber.